

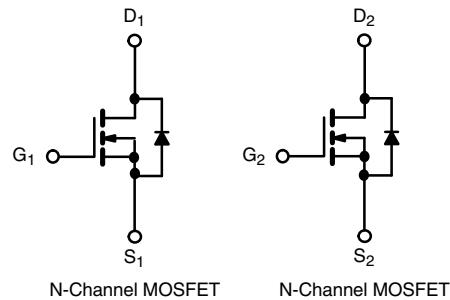
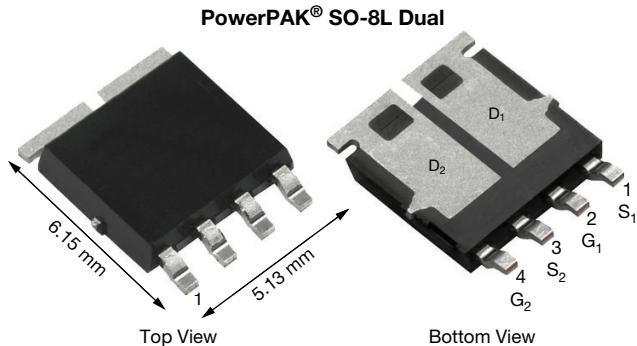
# Automotive Dual N-Channel 30 V (D-S) 175 °C MOSFET

<b>PRODUCT SUMMARY</b>	
V <sub>DS</sub> (V)	30
R <sub>DS(on)</sub> ( $\Omega$ ) at V <sub>GS</sub> = 10 V	0.0166
R <sub>DS(on)</sub> ( $\Omega$ ) at V <sub>GS</sub> = 4.5 V	0.0276
I <sub>D</sub> (A) per leg	8
Configuration	Dual
Package	PowerPAK SO-8L

## FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>g</sub> and UIS tested
- Material categorization:  
for definitions of compliance please  
see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE GRADE


**RoHS**  
COMPLIANT  
**HALOGEN FREE**


## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	
Continuous Drain Current <sup>a</sup>	I <sub>D</sub>	8	A
		8	
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	8	A
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	32	
Single Pulse Avalanche Current	I <sub>AS</sub>	23	mJ
Single Pulse Avalanche Energy	E <sub>AS</sub>	26	
Maximum Power Dissipation <sup>b</sup>	P <sub>D</sub>	48	W
		16	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260	

## THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient	R <sub>thJA</sub>	85	°C/W
Junction-to-Case (Drain)	R <sub>thJC</sub>	3.1	

### Notes

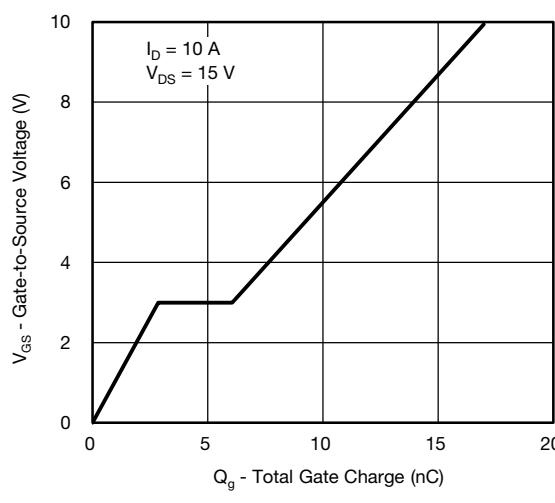
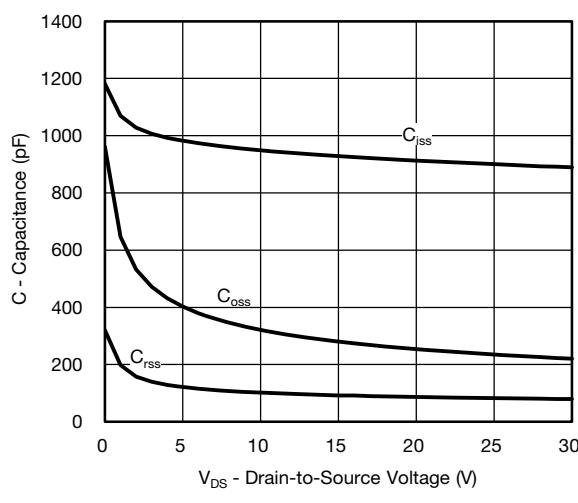
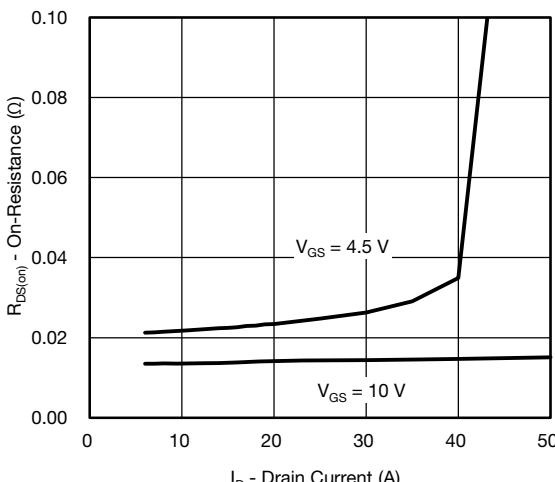
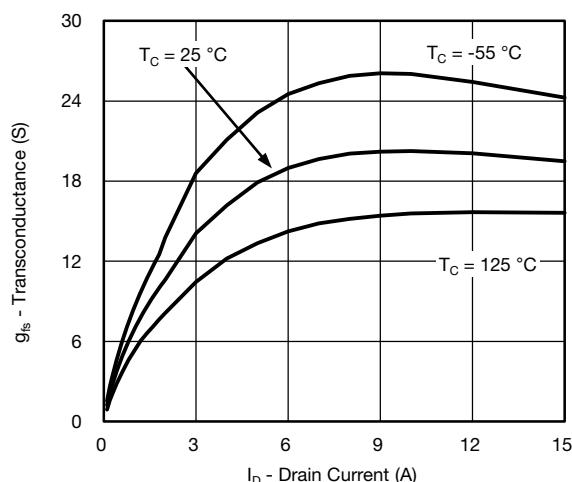
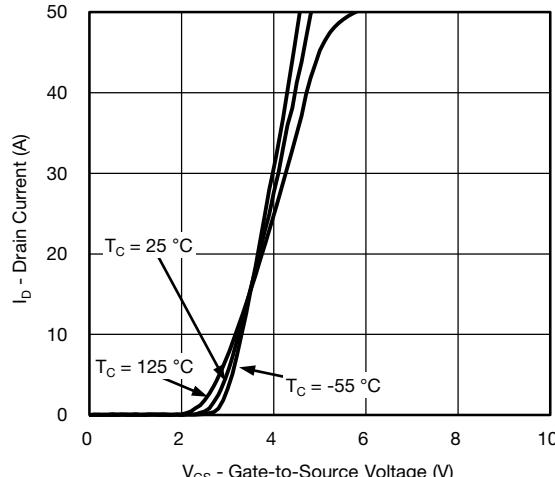
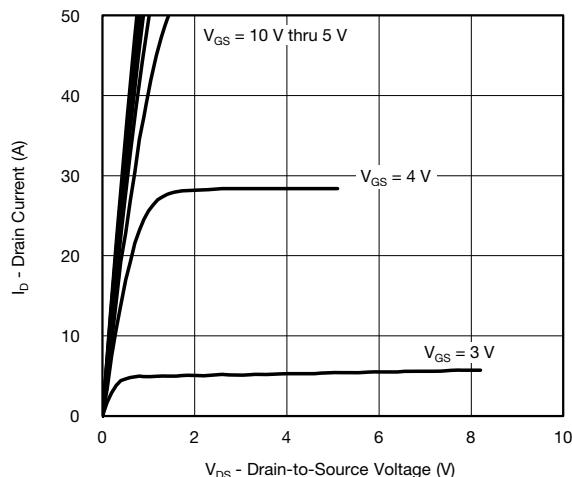
- Package limited.
- Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .
- When mounted on 1" square PCB (FR4 material).
- See solder profile ([www.vishay.com/doc?273257](http://www.vishay.com/doc?273257)). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

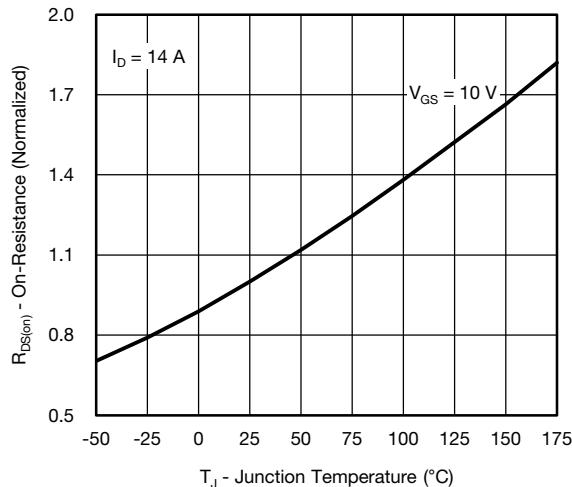
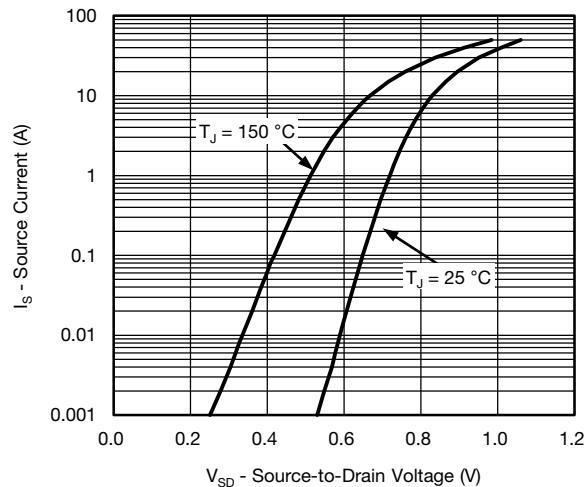
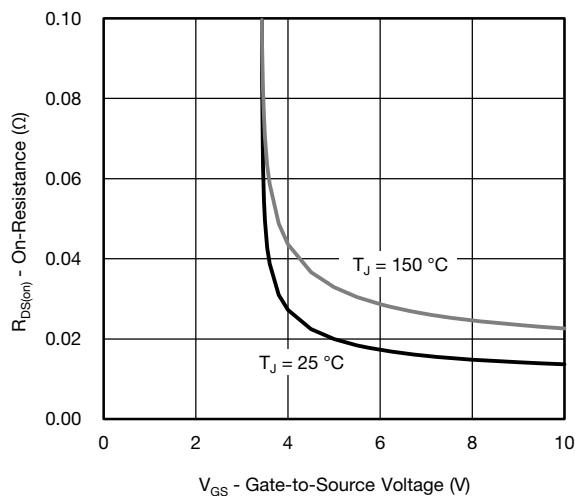
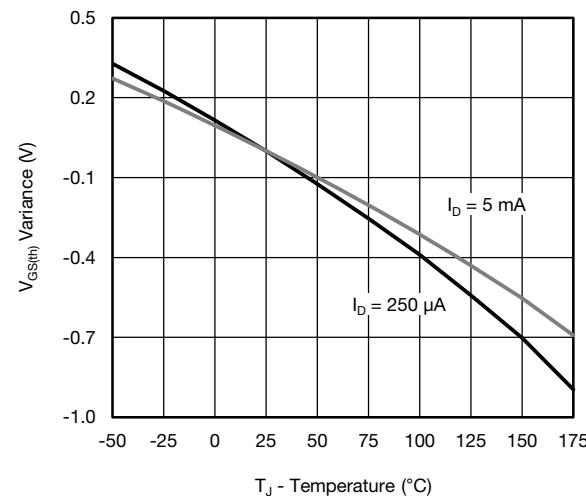
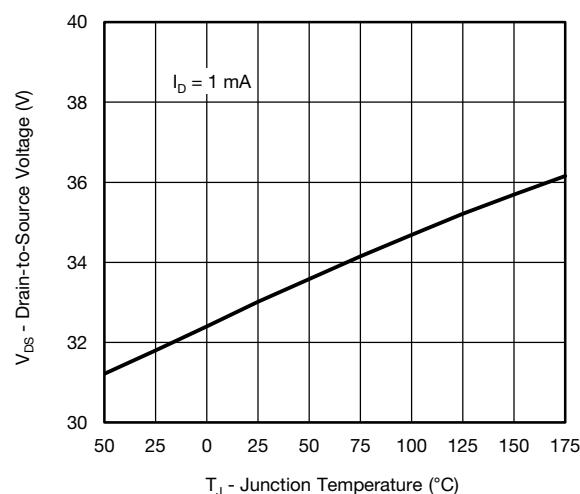
<b>SPECIFICATIONS</b> ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
<b>Static</b>								
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ , $I_D = 250 \mu\text{A}$		30	-	-	V	
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		1.5	2.0	2.5		
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$		-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0 \text{ V}$	$V_{DS} = 30 \text{ V}$	-	-	1	$\mu\text{A}$	
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 30 \text{ V}$ , $T_J = 125^\circ\text{C}$	-	-	50		
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 30 \text{ V}$ , $T_J = 175^\circ\text{C}$	-	-	150		
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{GS} = 10 \text{ V}$	$V_{DS} \geq 5 \text{ V}$	30	-	-	A	
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$	$I_D = 7.6 \text{ A}$	-	0.0138	0.0166	$\Omega$	
		$V_{GS} = 4.5 \text{ V}$	$I_D = 5.9 \text{ A}$	-	0.0230	0.0276		
		$V_{GS} = 10 \text{ V}$	$I_D = 7.6 \text{ A}$ , $T_J = 125^\circ\text{C}$	-	-	0.0252		
		$V_{GS} = 10 \text{ V}$	$I_D = 7.6 \text{ A}$ , $T_J = 175^\circ\text{C}$	-	-	0.0300		
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 7.6 \text{ A}$		-	20	-	S	
<b>Dynamic</b> <sup>b</sup>								
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$	$V_{DS} = 15 \text{ V}$ , $f = 1 \text{ MHz}$	-	929	1161	pF	
Output Capacitance	$C_{oss}$			-	280	350		
Reverse Transfer Capacitance	$C_{rss}$			-	93	116		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{GS} = 10 \text{ V}$	$V_{DS} = 15 \text{ V}$ , $I_D = 10 \text{ A}$	-	17	26	nC	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			-	3	-		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			-	3	-		
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$		1.1	-	5	$\Omega$	
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 15 \text{ V}$ , $R_L = 15 \Omega$ $I_D \geq 1 \text{ A}$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 6 \Omega$		-	4.5	7	ns	
Rise Time <sup>c</sup>	$t_r$			-	10	15		
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			-	20	30		
Fall Time <sup>c</sup>	$t_f$			-	7	10		
<b>Source-Drain Diode Ratings and Characteristics</b> <sup>b</sup>								
Pulsed Current <sup>a</sup>	$I_{SM}$			-	-	32	A	
Forward Voltage	$V_{SD}$	$I_F = 4.3 \text{ A}$ , $V_{GS} = 0$		-	0.8	1.2	V	

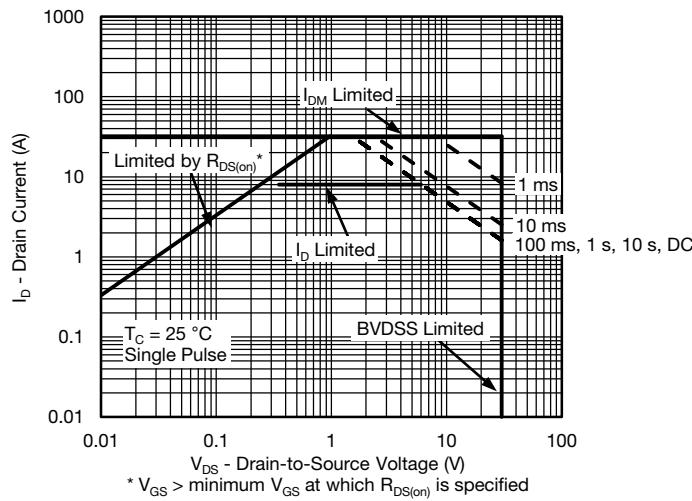
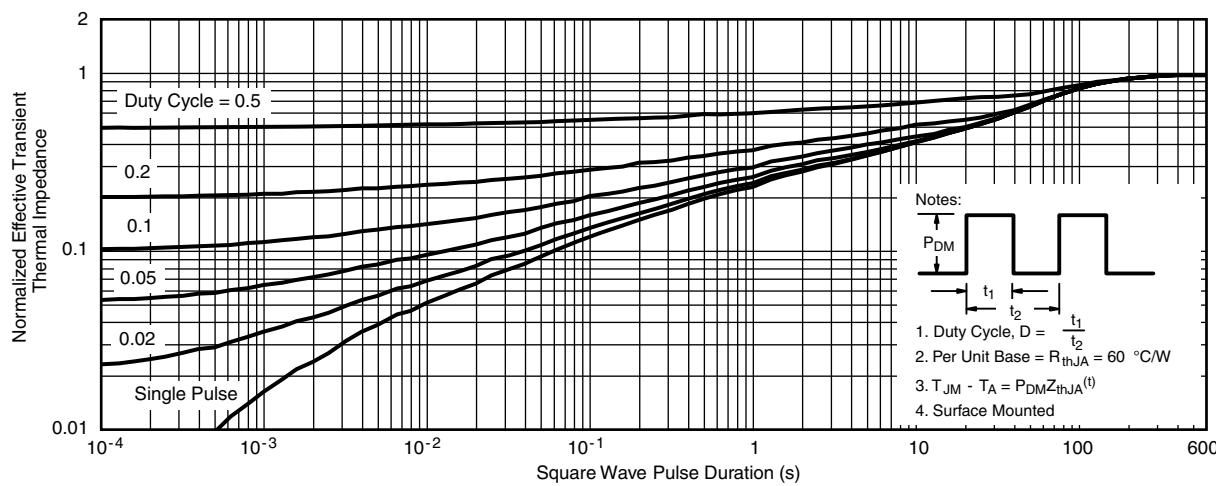
**Notes**

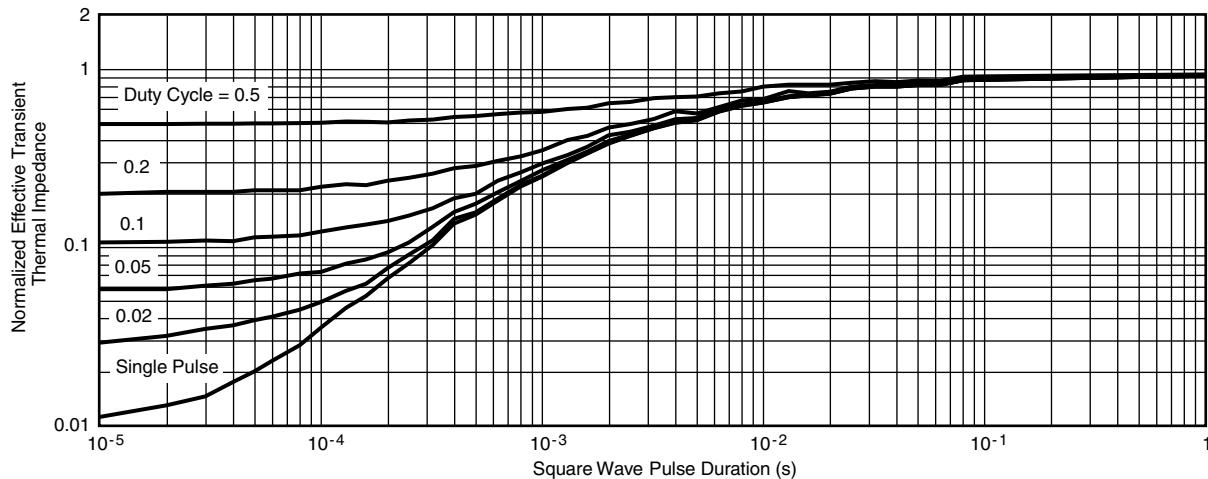
- a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)


**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

**On-Resistance vs. Junction Temperature**

**Source Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

**Threshold Voltage**

**Drain Source Breakdown vs. Junction Temperature**

**THERMAL RATINGS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

**Safe Operating Area**

**Normalized Thermal Transient Impedance, Junction-to-Ambient**

**THERMAL RATINGS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

**Normalized Thermal Transient Impedance, Junction-to-Case**
**Note**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient ( $25^\circ\text{C}$ )
  - Normalized Transient Thermal Impedance Junction-to-Case ( $25^\circ\text{C}$ )

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

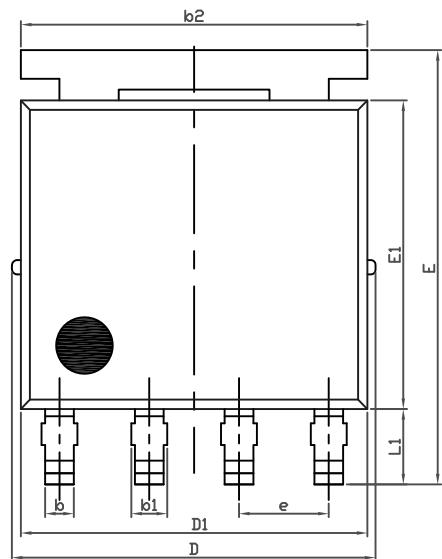
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?62832](http://www.vishay.com/ppg?62832).

REVISION HISTORY <sup>a</sup>		
REVISION	DATE	DESCRIPTION OF CHANGE
B	04-Aug-15	<ul style="list-style-type: none"><li>Revised R<sub>g</sub> minimum limit</li></ul>

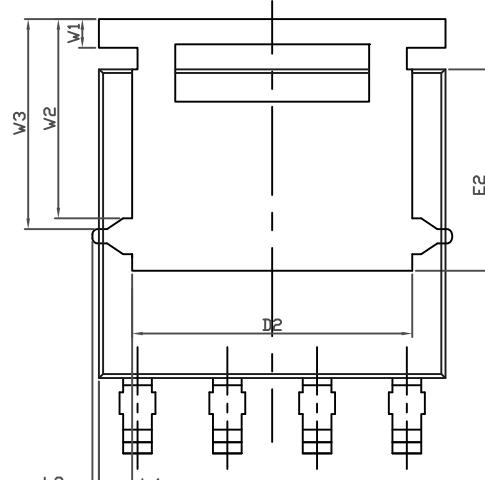
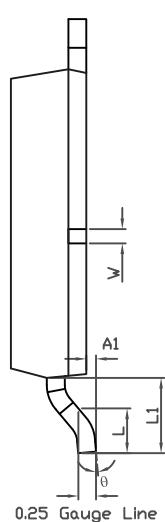
**Note**

a. As of April 2014

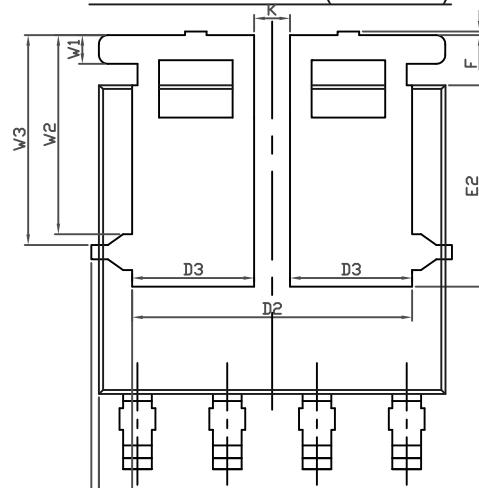
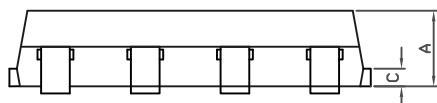
## PowerPAK® SO-8L Case Outline



TOPSIDE VIEW



BACKSIDE VIEW(SINGLE)



BACKSIDE VIEW(DUAL)



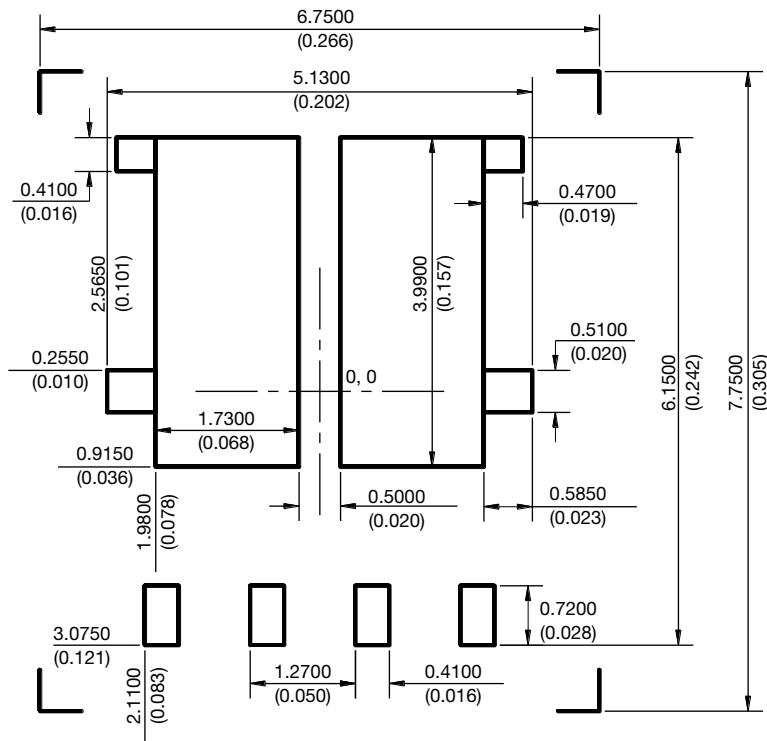
DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.00	1.07	1.14	0.039	0.042	0.045
A1	0.00	-	0.127	0.00	-	0.005
b	0.33	0.41	0.48	0.013	0.016	0.019
b1	0.44	0.51	0.58	0.017	0.020	0.023
b2	4.80	4.90	5.00	0.189	0.193	0.197
b3	0.094			0.004		
b4	0.47			0.019		
c	0.20	0.25	0.30	0.008	0.010	0.012
D	5.00	5.13	5.25	0.197	0.202	0.207
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.86	3.96	4.06	0.152	0.156	0.160
D3	1.63	1.73	1.83	0.064	0.068	0.072
e	1.27 BSC			0.050 BSC		
E	6.05	6.15	6.25	0.238	0.242	0.246
E1	4.27	4.37	4.47	0.168	0.172	0.176
E2 (for AI product)	2.75	2.85	2.95	0.108	0.112	0.116
E2 (for other product)	3.18	3.28	3.38	0.125	0.129	0.133
F	-	-	0.15	-	-	0.006
L	0.62	0.72	0.82	0.024	0.028	0.032
L1	0.92	1.07	1.22	0.036	0.042	0.048
K	0.51			0.020		
W	0.23			0.009		
W1	0.41			0.016		
W2	2.82			0.111		
W3	2.96			0.117		
θ	0°	-	10°	0°	-	10°

ECN: C12-0026-Rev. B, 27-Aug-12

DWG: 5976

**Note**

- Millimeters will gover

**RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL**


Recommended Minimum Pads  
Dimensions in mm (inches)  
Keep-out 6.75 (0.266) x 7.75 (0.305)



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- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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